

PATENT ABSTRACTS OF JAPAN

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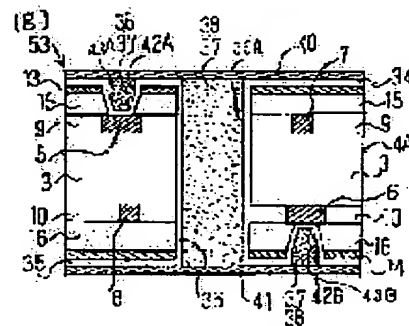
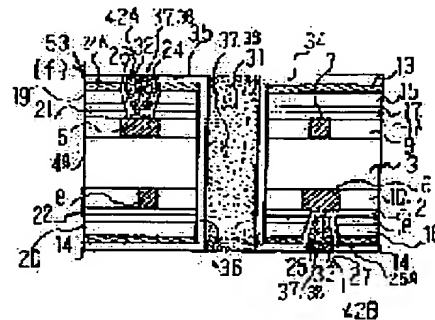
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(54) MANUFACTURE OF MULTILAYERED PRINTED CIRCUIT BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To improve electrical connection reliability by filling heat resistant conductive paste or the like in a penetrating through-hole and a hole of a via through-hole, smoothing the paste, then forming a copper-plating layer, and forming a land on a conductive via through-hole and a land on the conductive penetrating through-hole.

SOLUTION: Copper-plating layers 34, 35 are executed by an electrolytic copper plating method form via through-holes 42A, 42B and a penetrating through-hole 36, and solderless type nonconductor filler-contained insulating paste 37 or heat resistant conductive paste 38 is filled in the hole. Thereafter, the pastes 37, 38 projected from peripheries of the holes 42A, 42B and the hole 36 are emitted by a laser beam, smoothed, and then copper-plating layers 40, 41 are formed by an electrolytic copper-plating method. Then, the conductive via through-holes 42A, 42B, a conductive penetrating through-hole 36A, a land on the conductive via through hole, and a land on the conductive penetrating through-hole are formed by a photoetching method.



LEGAL STATUS

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